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11-28-2006



U.S. DEPARTMENT	OF COMMERCE
United States Patent and	Trademark Office

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below. 1. Name of conveying party(ies): 2. Name and address of receiving party(ies) Hidehisa Murase (11/8/2006), Yoshinari Sasaki Sony Corporation (11/9/2006), Kosei Aso (11/9/2006), and Naoki Yamada (11/8/2006) Internal Address: Yes X No Additional name(s) of conveying party(ies) attached? Street Address: 3. Nature of conveyance/Execution Date(s): 7-35 Kitashinagawa 6-Chome Shinagawa-Ku, Tokyo Execution Date(s): in parentheses after inventor name 141-0001 **JAPAN** x Assignment Merger Change of Name Joint Research Agreement Security Agreement Government Interest Assignment State: ___ Executive Order 9424, Confirmatory License Country: Zip: Additional name(s) & address(es) Other Yes x No attached? 4. Application or patent number(s): This document is being filed together with a new application. A. Patent Application No.(s) B. Patent No.(s) 11/515,896 Additional numbers attached? Yes 6. Total number of applications and 5. Name and address to whom correspondence concerning document should be mailed: patents involved: Ronald P. Kananen RADER, FISHMAN & GRAUER PLLC 7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00 Internal Address: Atty. Dkt.: SON-3616 Authorized to be charged by credit card Street Address: 1233 20th Street, N.W. Authorized to be charged to deposit account Suite 501 **Enclosed** None required (government interest not affecting title) City: Washington 8. Payment Information Zip: State: 20036 a. Credit Card Last 4 Numbers **Expiration Date** (202) 955-3750 Phone Number: (202) 955-3751 Fax Number: b. Deposit Account Number 18-0013 Authorized User Name Ronald P. Kananen rpk@raderfishman.com Email Address: 9. Signature:

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Ronald P. Kananen -24,104

Name of Person Signing

01 FC:8021

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PATENT REEL: 018604 FRAME: 0011

November 21, 2006 Date

Total number of pages including cover sheet, attachments, and documents:

Docket Number: SON-3616

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in LASER PROCESSING APPARATUS AND LASER PROCESSING METHOD AS WELL AS DEBRIS EXTRACTION

MECHANISM AND DEBRIS EXTRACTION METHOD

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address:

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome. Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention. said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration. the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto:

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention. applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 11/515.896 Filing Date: September 6.2006

This assignment executed on the dates indicated below.

Hidehisa MURASE	
Name of first or sole inventor	Execution date of U.S. Patent Application
Kanagawa, Japan	
Residence of first or sole inventor Hidekisa Murase	november 8, 2006
Signature of first or sole inventor	Date of this assignment

Date of this assignment

Yoshinari SASAKI	
Name of second inventor	Execution date of U.S. Patent Application
Tokyo, Japan	
Residence of second inventor	
John Sanh'	Nov タ 2006 Date of this assignment
Signature of second inventor	Date of this assignment
Kosei ASO	
Name of third inventor	Execution date of U.S. Patent Application
Kanagawa, Japan	
Residence of third inventor	
Kosei Aso	XOV. 09. 2006
Signature of third inventor	Date of this assignment
Naoki YAMADA	
Name of fourth inventor	Execution date of U.S. Patent Application
Kanagawa, Japan	
Posidones of fourth inventor	2 2 1
Jacobi Gamada	november 08, 2006
Signature of fourth inventor	Date of this assignment
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Name of fifth inventor	Execution date of U.S. Patent Application
Residence of fifth inventor	
Signature of 60h inventor	D.4 C.1:
Signature of fifth inventor	Date of this assignment

PATENT REEL: 018604 FRAME: 0013

RECORDED: 11/21/2006